1. (amended) A silicon wafer having a B-stageable underfill material deposited on one face of the wafer, the B-stageable underfill comprising a combination of two chemical compositions,

a first composition that is a liquid, or a solid dissolved or dispersed in a solvent, and

a second composition that is a solid or semi-solid material at room temperature, dispersible or dissolvable either in the first composition if the first composition is a liquid, or in the solvent for the first composition if the first composition is a solid dissolved or dispersed in a solvent,

the second composition having a curing temperature or curing temperature range higher than the curing temperature or curing temperature range of the first composition,

the ~~having~~ curing temperatures or curing temperature ranges sufficiently separated to allow ~~the composition with the lower curing temperature,~~ the first composition~~,~~ to cure without curing the ~~composition with the higher curing temperature, the~~ second composition,

characterized in that the first composition has been cured and the second composition is uncured.

7. (amended) A B-stageable underfill composition comprising a combination of two chemical compositions,

a first composition that is a liquid, or a solid dissolved or dispersed in a solvent, and

a second composition that is a solid or semi-solid material at room temperature, dispersible or dissolvable either in the first composition if the first composition is a liquid, or in the solvent for the first composition if the first composition is a solid dissolved or dispersed in a solvent,

the second composition having a curing temperature or curing temperature range higher than the curing temperature or curing temperature range of the first composition,

the ~~having~~ curing temperatures or curing temperature ranges sufficiently separated to allow ~~the composition with the lower curing temperature,~~ the first composition~~,~~ to cure without curing the ~~composition with the higher curing temperature, the~~ second composition.